

DATA SHEET

Silicon Beamless Schottky Diodes: Pairs and Quads

Applications

- Microwave MIC assembly and automated high volume manufacturing lines
- Mixers

Features

- Mechanically rugged design
- Three barrier heights for optimized mixer performance
- Wide product range: series pair, ring, bridge, and eight-diode rings
- Use in ring or crossover designs in double balanced mixers
- Virtually any LO requirement can be met with choice of barrier height
- 100% DC tested on water
- Available on film frame or waffle pack



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Skyworks GreenTM products are compliant with all applicable legislation and are halogen-free. For additional information, refer to *Skyworks Definition of Green*TM, document number SQ04-0074.

Description

Skyworks beamless diode family is designed for a high degree of device reliability in both commercial and industrial uses. The diodes are designed to offer the utmost in performance as well as achieving price sensitive cost targets for commercial systems.

Assembly and Handling Procedure

The process flow for assembly is:

- Die attach using nonconductive epoxy
- · Wire bond
- Encapsulation (nonconductive epoxy)





Die Attach Methods

All leadless chips are compatible with both eutectic and conductive epoxy die attach methods. Eutectic processes use Sn/Au or Sn/Pb solder. Nonconductive die attach is recommended.

Packing Methods

- 1. Gel pak
- 2. Wafer on film frame (rejects are marked with ink):
 - Diced, ready for pick and place
 - Unsawn, whole wafer, 7-mil thick, maximum

Wire Bonding

Two methods can be used to connect wire, ribbon, or wire mesh to the chips:

- Thermocompression
- Ballbonding

Skyworks recommends use of pure gold wire.

Electrical and Physical Specifications

Absolute maximum ratings for the beamless Schottky diodes are provided in Table 1. Electrical specifications are noted in Table 2. SPICE model parameters are defined in Table 3.

A typical bonding configuration is illustrated in Figure 1.

Table 1. Absolute Maximum Ratings (Note 1)

Parameter	Symbol	Minimum	Maximum	Units	
Peak inverse voltage	PIV		VB	-	
Supply current	Імах		50	mA/V	
Power dissipation (CW)	Poiss		75	mW/junction	
Storage temperature	Тѕтс	– 65	+175	°C	
Operating temperature	Тор	-65	+150	°C	
Electrostatic discharge:	ESD				
Human Body Model (HBM), Class 0			< 250	V	

Note 1: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

CAUTION: Although this device is designed to be as robust as possible, electrostatic discharge (ESD) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times.

Table 2. Electrical Specifications (Per Junction) (1 of 2) (Note 1)

Part Number	Band	Barrier	VF IF = 1.0 mA (mV)		ΔVF IF = 1.0 mA (mV)	CJ (Note 2) VR = 0 V, f = 1 MHz (pF)		Rs IF = 5 mA (Ω)	V _B @ 10 μA (V)	Outline Drawing Number		
			Min	Max	Max	Min	Max	Max	Min			
Ring Quad (Note	Ring Quad (Note 3)											
DMF3926-000	S	Low	200	260	10	0.30	0.50	5	-	551-002		
DME3927-000	S	Medium	300	400	10	0.30	0.50	5	-	551-002		
DMJ3928-000	S	High	500	600	10	0.30	0.50	5	-	551-002		
DMF3942-000	Х	Low	250	310	10	0.15	0.30	8	ı	551-002		
DME3943-000	Х	Medium	325	425	10	0.15	0.30	8	ı	551-002		
DMJ3944-000	Х	High	550	650	10	0.15	0.30	8	ı	551-002		
Bridge Quad (No	Bridge Quad (Note 3)											
DMF3929-000	S	Low	200	260	10	0.30	0.50	5	2	551-004		
DME3930-000	S	Medium	300	400	10	0.30	0.50	5	3	551-004		
DMJ3931-000	S	High	500	600	10	0.30	0.50	5	4	551-004		
DMF4102-000	Х	Low	250	310	10	0.15	0.3	14	2	551-004		
DME4101-000	Х	Medium	325	425	10	0.15	0.3	14	3	551-004		
DMJ4103-000	Х	High	550	650	10	0.15	0.3	14	4	551-004		
Series Pair (Note	3)											
DMF3932-000	S	Low	200	260	10	0.30	0.50	5	2	551-012		
DME3933-000	S	Medium	300	400	10	0.30	0.50	5	3	551-012		
DMJ3934-000	S	High	500	600	10	0.30	0.50	5	4	551-012		
Back-to-Back Ring Series Pair (Note 3)												
DMF3935-000	S	Low	200	260	10	0.30	0.50	5	-	551-056		
DME3936-000	S	Medium	300	400	10	0.30	0.50	5	-	551-056		
DMJ3937-000	S	High	500	600	10	0.30	0.50	5	-	551-056		

Table 2. Electrical Specifications (Per Junction) (2 of 2) (Note 1)

Part Number	Band	Band	Barrier	V IF = 1 (m	=	ΔVF IF = 1.0 mA (mV)	VR = f = 1	ote 2) : 0 V, MHz :F)	Rs IF = 5 mA (Ω)	Vs @ 10 μA (V)	Outline Drawing Number
			Min	Max	Max	Min	Max	Max	Min	<u> </u>	
Octoquad Ring (Note 4)											
DMF3938-000	S-X	Low	400	520	15	0.15	0.30	16	-	556-020	
DME3939-000	S-X	Medium	600	800	15	0.15	0.30	16	-	556-020	
DMJ3940-000	S-X	High	1000	1200	15	0.15	0.30	16	-	556-020	
Back-to-Back Crossover Quad, to 6 GHz											
DMF3945-000	S	Low	200	260	15	0.30	0.50	5	-	588-065	
DME3946-000	S	Medium	300	400	15	0.30	0.50	5	-	588-065	
DMJ3947-000	S	High	525	625	15	0.30	0.50	5	-	588-065	

Note 1. Performance is guaranteed only under the conditions listed in this table.

Table 3. SPICE Model Parameters (Per Junction)

Part Number Prefix	Is (A)	Rs (Ω)	N	TT (s)	CJO (pF)	М	Eg (eV)	(A) An	ХТІ	Fc	Bv (V)	IBV (A)
DMF3926	2.5 x 10 ⁻⁷	4	1.04	1 x 10 ⁻¹¹	0.42	0.32	0.69	0.51	2	0.5	2	1 x 10 ⁻⁵
DME3927	1.3 x 10 ⁻⁹	4	1.04	1 x 10 ⁻¹¹	0.39	0.34	0.69	0.65	2	0.5	3	1 x 10 ⁻⁵
DMJ3926	9.0 x 10 ⁻¹³	4	1.04	1 x 10 ⁻¹¹	0.39	0.42	0.69	0.84	2	0.5	3	1 x 10 ⁻⁵
DMF4102	1.1 x 10 ⁻⁷	6	1.04	1 x 10 ⁻¹¹	0.22	0.32	0.69	0.495	2	0.5	2	1 x 10 ⁻⁵
DME4101	2.4 x 10 ⁻⁹	6	1.04	1 x 10 ⁻¹¹	0.20	0.37	0.69	0.595	2	0.5	3	1 x 10 ⁻⁵
DMJ4103	8.5 x 10 ⁻¹³	6	1.04	1 x 10 ⁻¹¹	0.20	0.42	0.69	0.800	2	0.5	4	1 x 10 ⁻⁵

Note 2: Cj represents total capacitance. Maximum Cj unbalance @ 0 V, 1 MHz = 0.25 pF.

Note 3: Matching criteria Vf @ 1 mA \leq 15 mV available for matched sets.

Note 4: Matching criteria Vf @ 1 mA \leq 20 mV available for matched sets.

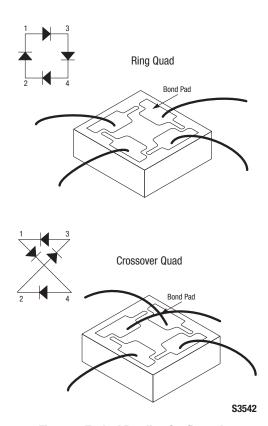


Figure 1. Typical Bonding Configuration

Package Information

Skyworks silicon beamless Schottky diodes are provided in Gel paks and on film frame. Package dimensions are provided in Figures 2 through 7.

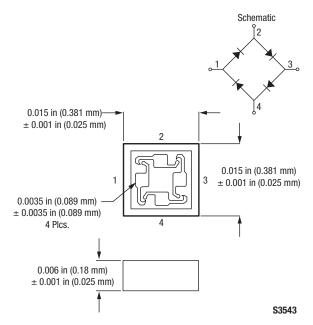


Figure 2. 551-002 Package Dimensions

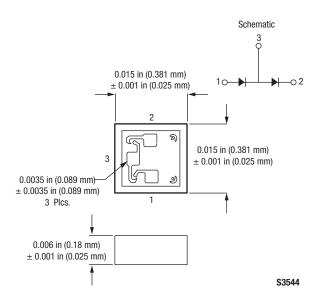


Figure 3. 551-012 Package Dimensions

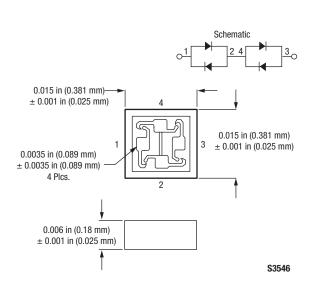


Figure 4. 551-056 Package Dimensions

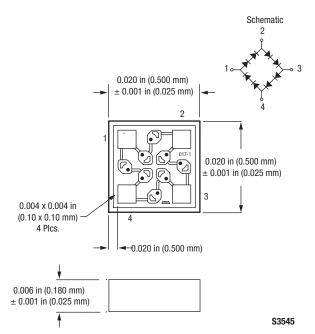


Figure 5. 556-020 Package Dimensions

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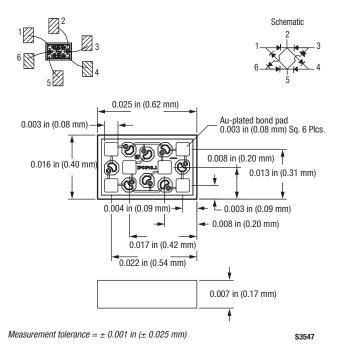


Figure 6, 588-065 Package Dimensions

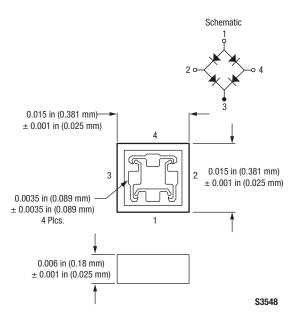


Figure 7. 551-004 Package Dimensions

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